NOTES:

1. MATERIALS:
   LEAD FRAME: COPPER 194FH, THK = 0.023 ± 0.008
   BODY: SEMICONDUCTOR MOLDING BIPOLAR, CONTACT QPTECHNOLOGIES FOR DETAILS.

2. FINISH:
   LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 250 TO 300 MICRONICHES (2.5-7.6um) THICK.
   GOLD PLATE PER MIL-G-45204, TYPE A, GRADE A, CLASS 1 (40 TO 80 MICRONICHES (1-2um) THICK).
   BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)

3. PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.

4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.

5. PACKAGE CONFORMS TO JEDEC MO-220